molex

Part Number: 879331219

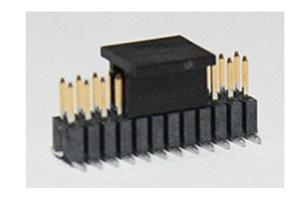
Product Description: Slim-Grid Header, 12 Circuits, Surface Mount, Vertical, Unshrouded, 0.05µm Overall Gold (Au) Plated, with Pick-

and-Place Cap, Tube, Lead-Free

Series Number: 87933

Status: New Business Not Supported Product Category: Board-to-Board

Connectors



Documents & Resources

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 34; 33;
China RoHS	©
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	New Business Not Supported
Category	Board-to-Board Connectors
Series	87933
Description	Slim-Grid Header, 12 Circuits, Surface Mount, Vertical, Unshrouded, 0.05µm Overall Gold (Au) Plated, with Pick-and-Place Cap, Tube, Lead-Free
Application	Board-to-Board, Signal
Comments	4.3 Amps per Pole with only 1 contact powered up; 1.4 Amps per Pole with max contacts powered up
Component Type	PCB Header
Product Family	Slim-Grid Board-to-Board Connectors
Product Name	Slim-Grid
UPC	191128087780

Electrical

Current - Maximum per Contact	1.4A
Voltage - Maximum	125V AC

Physical

Breakaway	Yes
Circuits (Loaded)	12
Circuits (maximum)	12
Color - Resin	Black
Durability (mating cycles max)	500
First Mate / Last Break	No
Glow-Wire Capable	No
Guide to Mating Part	No
Keying to Mating Part	None
Lock to Mating Part	None
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Gold

Material - Resin	Liquid Crystal Polymer
Net Weight	0.204/g
Number of Rows	2
Orientation	Vertical
Packaging Type	Tube
PCB Locator	No
PCB Retention	None
Pitch - Mating Interface	1.27mm
Pitch - Termination Interface	1.27mm
Plating min - Mating	0.051µm
Plating min - Termination	0.051µm
Polarized to Mating Part	No
Polarized to PCB	No
Robotic Placement	Pick and Place Cap
Shrouded	No
Temperature Range - Operating	-55° to +105°C
Termination Interface Style	Surface Mount

Solder Process Data

Max-Duration	11
Lead-Free Process Capability	REFLOW
Max-Cycle	1
Max-Temp	260

This document was generated on Dec 11, 2023